

REVISIONS			
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
A	Added device types 02 and 03. Made changes to 1.3 and 1.4. Made technical changes to table I. Made changes to figures 1 and 2. Updated drawing to reflect MIL-H-38534 processing.	90-11-19	Monica Poelking
B	Added vendor CAGE 31757. Editorial changes throughout.	91-09-17	Monica Poelking
C	Added vendor to 5962-87679032X and added footnote 2 to the 5962-87679012X vendor specified to incorrect military part number. Editorial changes throughout.	92-05-14	Gregory Lude
D	Changes in accordance with NOR 5962-R264-92.	92-07-27	Alan Barone
E	Add case outlines T, U, X, and Y. Rewrite entire document.	93-08-02	K. A. Cottongim
F	Added device type 04 with cage 50434. Added case outline F to paragraph 1.2.3. Redrew entire document.	96-02-29	K. A. Cottongim
G	Changes in accordance with NOR 5962-R162-96.	96-06-24	Kendall A. Cottongim
H	Added class K devices. Redrew entire document. -sld	98-04-09	K. A. Cottogim
J	Paragraph 1.2.2, correct generic numbers for device types 01 and 05. Table I, Input to output insulation leakage current test (I_{IO}), conditions column, change; relative humidity = 45 percent to relative humidity \leq 65 percent. Editorial changes throughout.	04-10-21	Raymond Monnin

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

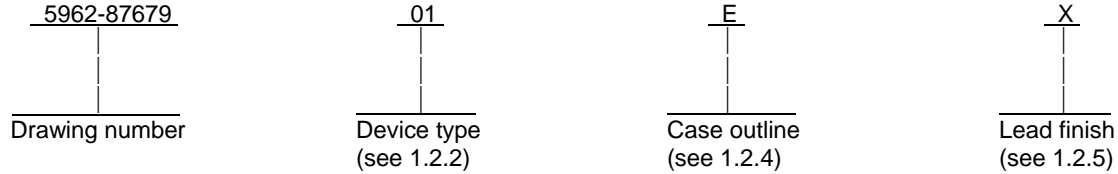
REV																				
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REV STATUS		REV	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J	J
OF SHEETS		SHEET	1	2	3	4	5	6	7	8	9	10	11	12	13	14				
PMIC N/A		PREPARED BY	Donald Osborne																	
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A		CHECKED BY	Steve L. Duncan																	
		APPROVED BY	Monica Poelking																	
		DRAWING APPROVAL DATE	88-06-03																	
		REVISION LEVEL	J																	
		SIZE	CAGE CODE																	
		A	67268		5962-87679															
		SHEET	1 OF 15																	

1. SCOPE

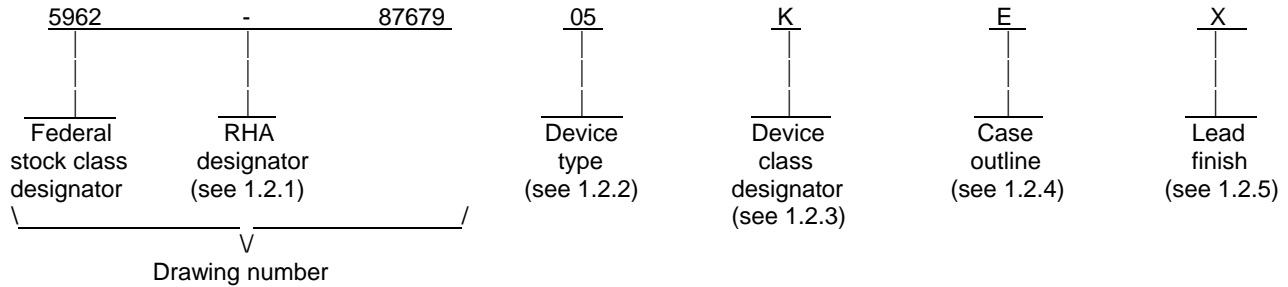
1.1 Scope. This drawing documents five product assurance classes as defined in paragraph 1.2.3 and MIL-PRF-38534. A choice of case outlines and lead finishes which are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.

1.2 PIN. The PIN shall be as shown in the following example:

For class H devices:



For class K devices:



1.2.1 Radiation hardness assurance (RHA) designator. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) shall identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	4N55, 66024-001A	Dual channel, optocoupler with separate supply voltage and ground connections
02	HCPL-5531	Dual channel, optocoupler with common supply voltage and ground connections
03	HCPL-6531, 66125	Dual channel, optocoupler with separate supply voltage connections
04	HCPL-6551	Quad channel, optocoupler with common supply voltage and ground connections
05	HCPL-257K, 66024-300A	Dual channel, optocoupler with separate supply voltage and ground connections
06	HCPL-553K, 66124-300	Dual channel, optocoupler with common supply voltage and ground connections
07	HCPL-653K	Dual channel, optocoupler with separate supply voltage connections
08	HCPL-655K	Quad channel, optocoupler with common supply voltage and ground connections

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1.2.3 Device class designator. This device class designator shall be a single letter identifying the product assurance level. All levels are defined by the requirements of MIL-PRF-38534 and require QML Certification as well as qualification (Class H, K, and E) or QML Listing (Class G and D). The product assurance levels are as follows:

<u>Device class</u>	<u>Device performance documentation</u>
K	Highest reliability class available. This level is intended for use in space applications.
H	Standard military quality class level. This level is intended for use in applications where non-space high reliability devices are required.
G	Reduced testing version of the standard military quality class. This level uses the Class H screening and In-Process Inspections with a possible limited temperature range, manufacturer specified incoming flow, and the manufacturer guarantees (but may not test) periodic and conformance inspections (Group A, B, C, and D).
E	Designates devices which are based upon one of the other classes (K, H, or G) with exception(s) taken to the requirements of that class. These exception(s) must be specified in the device acquisition document; therefore the acquisition document should be reviewed to ensure that the exception(s) taken will not adversely affect system performance.
D	Manufacturer specified quality class. Quality level is defined by the manufacturers internal, QML certified flow. This product may have a limited temperature range.

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
E	CDIP2-T16	16	Dual-in-line
P	CDIP2-T8	8	Dual-in-line
T	See figure 1	16	Dual-in-line
U	See figure 1	16	Dual-in-line
X	See figure 1	8	Dual-in-line
Y	See figure 1	8	Dual-in-line
2	CQCC1-N20	20	Square leadless chip carrier
F	CDFP4-F16	16	Flat package

1.2.5 Lead finish. The lead finish shall be as specified in MIL-PRF-38534.

1.3 Absolute maximum ratings. 1/

Supply voltage range (each channel).....	-0.5 V dc to +20 V dc
Output voltage range (each channel).....	-0.5 V dc to +20 V dc
Reverse input voltage (each channel)	
Device types 01 and 05	5.0 V dc
Device types 02, 03, 04, 06, 07, and 08.....	3.0 V dc
Output current (each channel)	8 mA dc
Input current (each channel)	20 mA dc
Peak input current (each channel \leq 1 ms duration 500 pps)	40 mA dc
Emitter base reverse voltage (each channel) 2/	3.0 V dc
Output power dissipation (each channel) 3/	50 mW
Input power dissipation (each channel).....	36 mW
Storage temperature range	-65°C to +150°C
Lead temperature (soldering, 10 seconds) 4/	+260°C
Junction temperature (T _j)	+150°C

1/ Unless otherwise specified, all voltages are referenced to ground.

2/ This parameter applies to the 01, 03, 05, and 07 device types only.

3/ Output power is collector power plus V_{CC} supply power for that channel. Derate linearly 1.4 mW/°C above +100°C. Derating applies to device types 01 and 05 only.

4/ 1.6 mm below seating plane. This applies to device types 01, 02, 05, and 06 only.

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1.4 Recommended operating conditions.

Supply voltage range (V_{CC}) (each channel).....	2.0 V dc minimum to 18.0 V dc maximum
Low level input current (each channel).....	250 μ A dc maximum
Case operating temperature range (T_C).....	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATION

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
 MIL-STD-1835 - Interface Standard for Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
 MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <http://assist.daps.dla.mil/quicksearch/> or www.dodssp.daps.mil or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. The manufacturer may eliminate, modify or optimize the tests and inspections herein, however the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. In addition, the modification in the QM plan shall not affect the form, fit, or function of the device for the applicable device class.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

3.2.3 Switching test circuit and waveform(s). The switching test circuit and waveform(s) shall be as specified on figure 3.

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3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking of device(s). Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked.

3.6 Data. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.

3.7 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:

- a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.
- b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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TABLE I. Electrical performance characteristics.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _C ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
<u>INPUT</u>								
Forward voltage (each channel)	V _F	I _F = 20 mA	1,2,3	01,05		1.80	V dc	
				02,03,04, 06,07,08		1.90		
Reverse breakdown voltage (each channel)	BV _R	I _R = 10 μA	1,2,3	01,05	5.0		V dc	
				02,03,04, 06,07,08	3.0			
<u>COUPLED</u>								
High level output current (each channel)	I _{OH}	V _O = V _{CC} = 18 V <u>2/</u>	1,2,3	All		100	μA dc	
Output leakage current (each channel)	I _{OLEAK}	V _O = V _{CC} = 18 V <u>3/</u>	1,2,3	All		250	μA dc	
Current transfer ratio (each channel) <u>4/</u>	CTR	V _{CC} = 4.5 V, V _O = 0.4 V, I _F = 16 mA	1,2,3	All	9		%	
Input to output insulation leakage current <u>5/</u>	I _{I/O}	T _C = +25°C, V _{I/O} = 1500 V, Relative humidity ≤ 65 percent, t = 5 s	1	All		1.0	μA dc	
Supply current (each channel)	High level	<u>2/</u>	1,2,3	01,03,05, 07		10	μA dc	
				04,08		40		
				02,06		20		
	Low level	I _{CCL}	I _{F1} = I _{F2} = 20 mA, I _{F3} = I _{F4} = 20 mA <u>6/</u>	1,2,3	01,03,05, 07		200	μA dc
					04,08		800	
					02,06		400	

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Test	Symbol	Conditions <u>1/</u> -55°C ≤ T _C ≤ +125°C unless otherwise specified	Group A subgroups	Device type	Limits		Unit	
					Min	Max		
Propagation delay time (each channel)	High to low	t _{PHL}	I _F = 16 mA, R _L = 8.2 kΩ, V _{CC} = 5.0 V, C _L = 50 pF See figure 3	9,10,11	All		2	μs
	Low to high	t _{PLH}	I _F = 16 mA, R _L = 8.2 kΩ, V _{CC} = 5.0 V, C _L = 50 pF See figure 3	9,10,11	All		6	μs

1/ V_{CC} = 18 V dc unless otherwise specified.

2/ I_F = 0 mA for channel under test and I_F = 20 mA for the other channels.

3/ I_F = 250 μA for channel under test and I_F = 20 mA for the other channels.

4/ Current transfer ratio is defined as the ratio of output collector current I_O to the forward LED input current, I_F, times 100 percent.

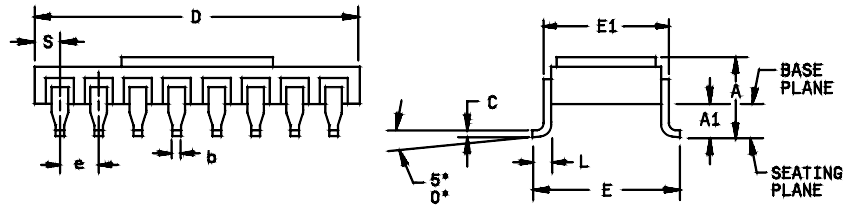
5/ All devices are considered two terminal devices: Measured between all input leads or terminals shorted together and all output leads or terminals shorted together.

6/ I_{F3} and I_{F4} apply to device types 04 and 08 only.

7/ I_F = 0 mA for channel under test and I_F = 0 mA for the other channels.

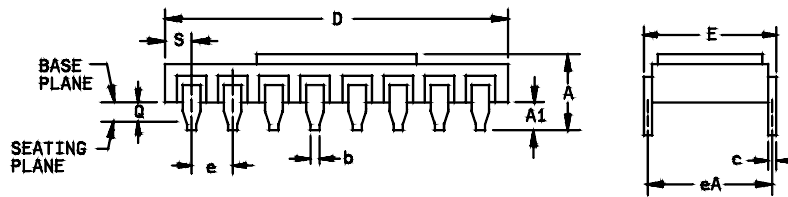
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Case outline T.



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A		4.57		.180
A1	1.40	1.65	.055	.065
b	0.41	0.51	.016	.020
c	0.18	0.33	.007	.013
D	20.07	20.83	.790	.820
e	2.29	2.79	.090	.110
E	9.65	9.91	.380	.390
E1		8.13		.320
L	1.07	1.32	.042	.052
S	0.89	1.52	.035	.060

Case outline U.



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A		4.32		.170
A1	1.14	1.40	.045	.055
b	0.41	0.51	.016	.020
c	0.18	0.33	.007	.013
D	20.07	20.83	.790	.820
e	2.29	2.79	.090	.110
E		8.13		.320
eA	7.37	7.87	.290	.310
Q	0.51		.020	
S	0.89	1.52	.035	.060

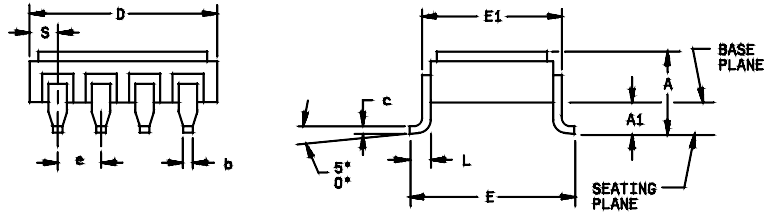
NOTES:

1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
2. Pin 1 is indicated by the ESD triangle(s) marked on top of the package.

FIGURE 1. Case outline(s).

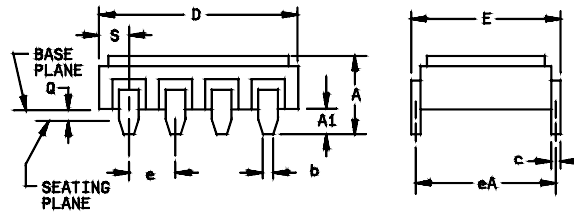
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Case outline X.



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A		4.57		.180
A1	1.40	1.65	.055	.065
b	0.41	0.51	.016	.020
c	0.18	0.33	.007	.013
D	9.40	9.91	.370	.390
e	2.29	2.79	.090	.110
E	9.65	9.91	.380	.390
E1		8.13		.320
L	1.07	1.32	.042	.052
S	0.89	1.27	.035	.050

Case outline Y.



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A		4.32		.170
A1	1.14	1.40	.045	.055
b	0.41	0.51	.016	.020
c	0.18	0.33	.007	.013
D	9.40	9.91	.370	.390
e	2.29	2.79	.090	.110
E		8.13		.320
eA	7.37	7.87	.290	.310
Q	0.51		.020	
S	0.89	1.27	.035	.050

NOTES:

1. The U.S. government preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.
2. Pin 1 is indicated by a dot marked on top of the package.

FIGURE 1. Case outline(s) - Continued.

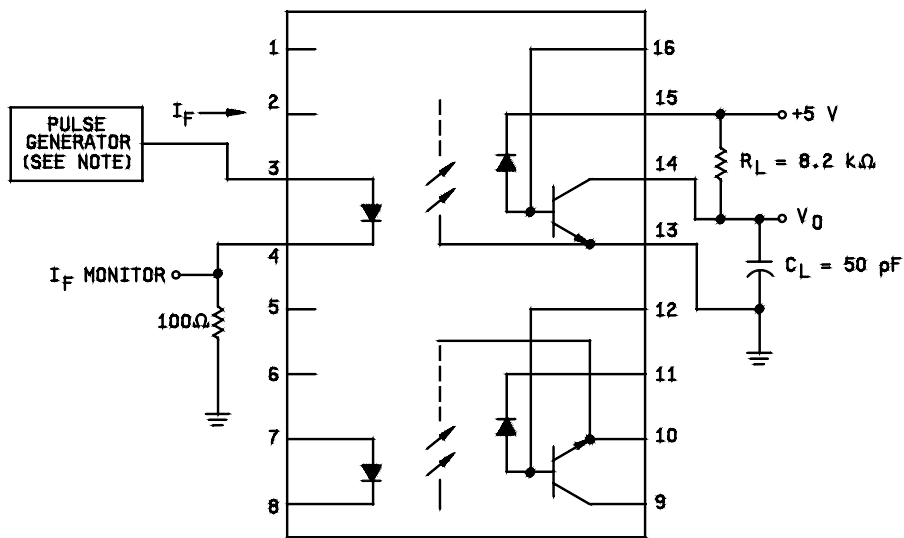
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Device types	01 and 05	02 and 06	03 and 07	04 and 08
Case outlines	E, T, and U	P, X, and Y	2	F
Terminal number	Terminal symbol			
1	NC	+VF1 (anode)	NC	-VF1 (cathode)
2	NC	-VF1 (cathode)	-VF1 (cathode)	+VF1 (anode)
3	+VF1 (anode)	-VF2 (cathode)	+VF1 (anode)	+VF2 (anode)
4	-VF1 (cathode)	+VF2 (anode)	NC	-VF2 (cathode)
5	NC	GND	NC	-VF3 (cathode)
6	NC	VO2	NC	+VF3 (anode)
7	+VF2 (anode)	VO1	Ground 1	+VF4 (anode)
8	-VF2 (cathode)	V _{CC}	VO1	-VF4 (cathode)
9	VO2	---	VB1	NC
10	Ground 2	---	V _{CC1}	GROUND
11	V _{CC2}	---	NC	VO4
12	VB2	---	Ground 2	VO3
13	Ground 1	---	VO2	VO2
14	VO1	---	VB2	VO1
15	V _{CC1}	---	V _{CC2}	V _{CC}
16	VB1	---	NC	NC
17	---	---	NC	---
18	---	---	NC	---
19	---	---	+VF2 (anode)	---
20	---	---	-VF2 (cathode)	---

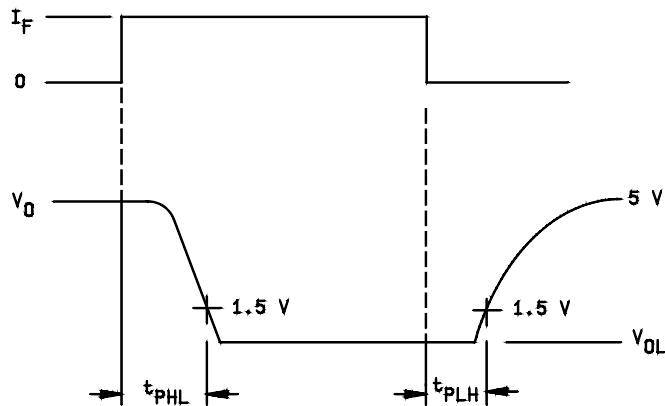
FIGURE 2. Terminal connections.

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Device types 01 and 05.
(Each channel)



10% DUTY CYCLE
 $1/f < 100 \mu\text{s}$

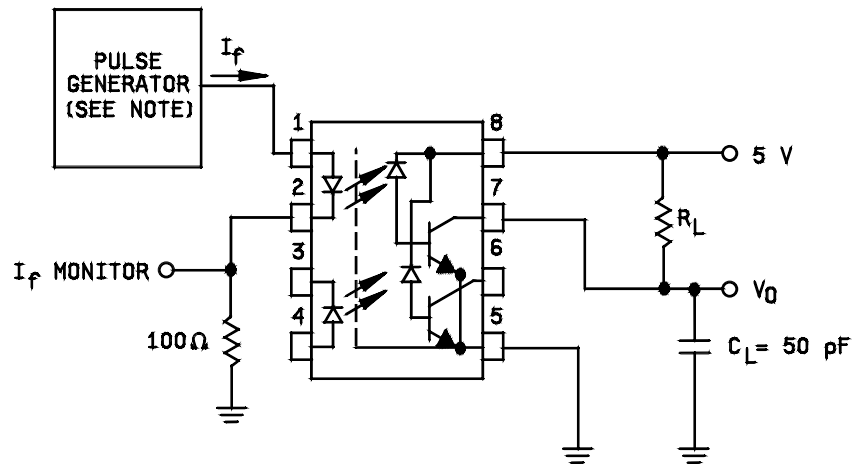


NOTE: All input pulses are supplied by generators having the following characteristics: $Z_0 = 50\Omega$; $t_r = 5 \text{ ns}$.

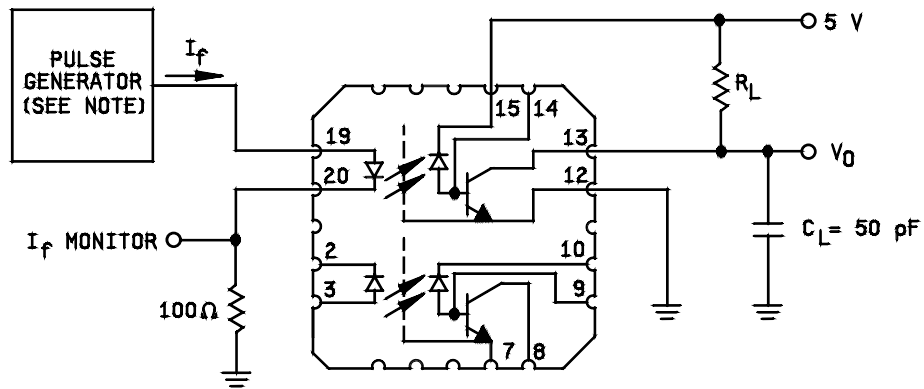
FIGURE 3. Switching test circuit and waveforms.

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Device types 02 and 06.
(Each channel)



Device types 03 and 07.
(Each channel)

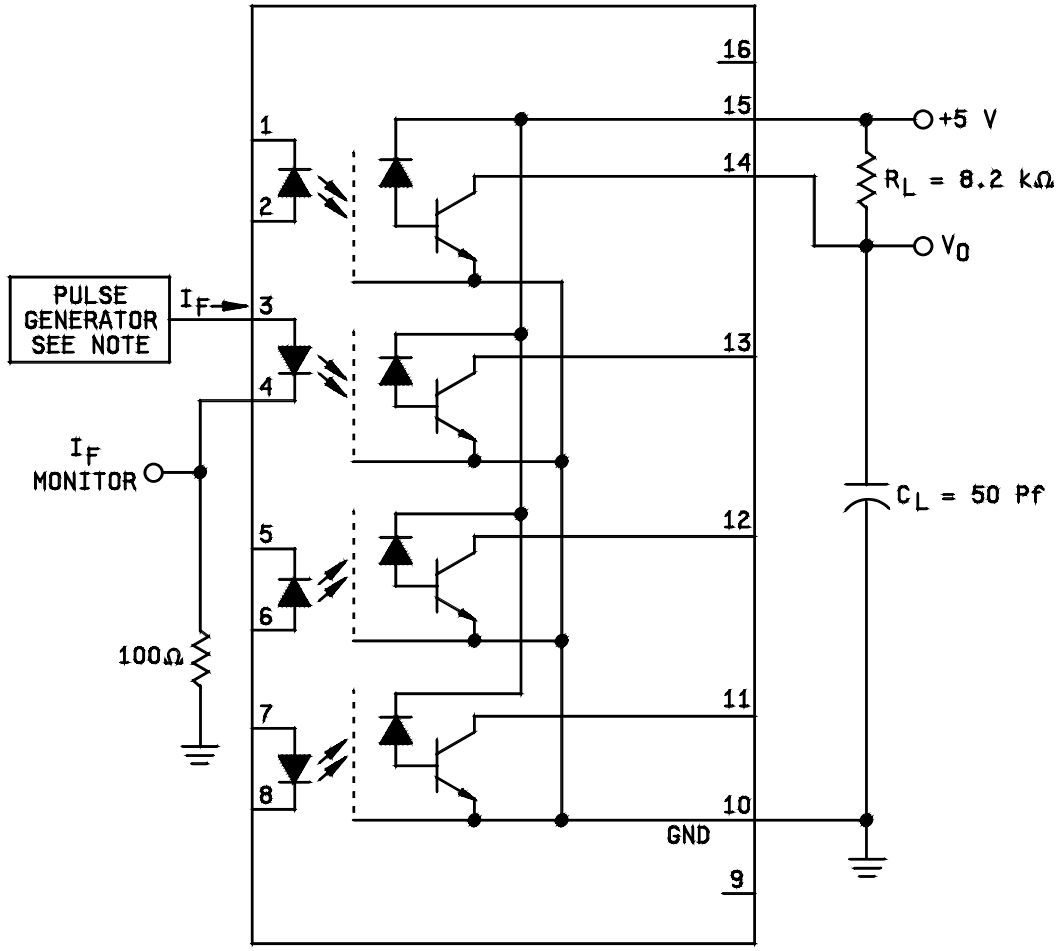


NOTE: All input pulses are supplied by generators having the following characteristics: $Z_0 = 50\Omega$; $t_r = 5 \text{ ns}$.

FIGURE 3. Switching test circuit and waveforms - Continued.

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Device types 04 and 08.
(Each channel)



NOTE: All input pulses are supplied by generators having the following characteristics: $Z_o = 50\Omega$; $t_r = 5 \text{ ns}$.

FIGURE 3. Switching test circuit and waveforms - Continued.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	1
Final electrical parameters	1*,2,3,9
Group A test requirements	1,2,3,9,10,11
Group C end-point electrical parameters	1,2,3
End-point electrical parameters for radiation hardness assurance (RHA) devices	Not applicable

* PDA applies to subgroup 1.

4.3 Conformance and periodic inspections. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.

4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, 6, 7, and 8 shall be omitted.

4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

4.3.5 Radiation Hardness Assurance (RHA) inspection. RHA inspection is not currently applicable to this drawing.

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated as specified in MIL-PRF-38534.

6.4 Record of users. Military and industrial users shall inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.5 Comments. Comments on this drawing should be directed to DSCC-VA, Post Office Box 3990, Columbus, Ohio 43218-3990, or telephone (614) 692-1081.

6.6 Sources of supply. Sources of supply are listed in MIL-HDBK-103 and QML-38534. The vendors listed in MIL-HDBK-103 and QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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Approved sources of supply for SMD 5962-87679 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38534 during the next revisions. MIL-HDBK-103 and QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin information is superseded by the next dated revisions of MIL-HDBK-103 and QML-38534.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-8767901EA 5962-8767901EA 5962-8767901EC 5962-8767901EC	31757 50434 31757 50434	66024-001A 4N55/883B#200 66024-001A 4N55/883B
5962-8767901TA 5962-8767901TA 5962-8757901TC	31757 50434 31757	66024-001J 4N55/883B#300 66024-001J
5962-8767901UA 5962-8767901UC	50434 50434	4N55/883B#100 4N55/883B#100
5962-87679012A	<u>3</u> /	66125-001
5962-8767902PA 5962-8767902PA 5962-8767902PC 5962-8767902PC	31757 50434 31757 50434	66126-103 HCPL-5531#200 (*) 66126-103 HCPL-5531 (*)
5962-8767902XA 5962-8767902XA 5962-8767902XC	31757 50434 31757	66126-103J HCPL-5531#300 (*) 66126-103J
5962-8767902YA 5962-8767902YC	50434 50434	HCPL-5531#100 (*) HCPL-5531#100 (*)
5962-87679032A 5962-87679032A 5962-87679032C	31757 50434 31757	66125-001 HCPL-6531 66125-001
5962-8767904FC	50434	HCPL-6551 (*)
5962-8767905KEA 5962-8767905KEA 5962-8767905KEC 5962-8767905KEC	31757 50434 31757 50434	66024-300A HCPL-257K#200 (*) 66024-300A HCPL-257K
5962-8767905KTA 5962-8767905KTA 5962-8767905KTC	31757 50434 31757	66024-300T HCPL-257K#300 66024-300T
5962-8767905KUA 5962-8767905KUC	50434 50434	HCPL-257K#100 HCPL-257K#100

See footnotes at end of table.

STANDARD MICROCIRCUIT DRAWING BULLETIN - Continued.

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Standard microcircuit drawing PIN <u>1/</u>	Vendor CAGE number	Vendor similar PIN <u>2/</u>
5962-8767906KPA 5962-8767906KPA 5962-8767906KPC 5962-8767906KPC	31757 50434 31757 50434	66126-300 HCPL-553K#200 (*) 66126-300 HCPL-553K (*)
5962-8767906KXA 5962-8767906KXA 5962-8767906KXC	31757 50434 31757	66126-300J HCPL-553K#300 (*) 66126-300J
5962-8767906KYA 5962-8767906KYC	50434 50434	HCPL-553K#100 (*) HCPL-553K#100 (*)
5962-8767907K2A 5962-8767907K2A	31757 50434	66125-300 HCPL-653K
5962-8767908KFC	50434	HCPL-655K (*)

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from a QML source.

Vendor CAGE number

Vendor name and address

31757

Micropac Industries, Incorporated
905 East Walnut Street
Garland, TX 75040

50434

Agilent Technologies
Semiconductor Products Group
350 West Trimble Road
San Jose, CA 95131

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.